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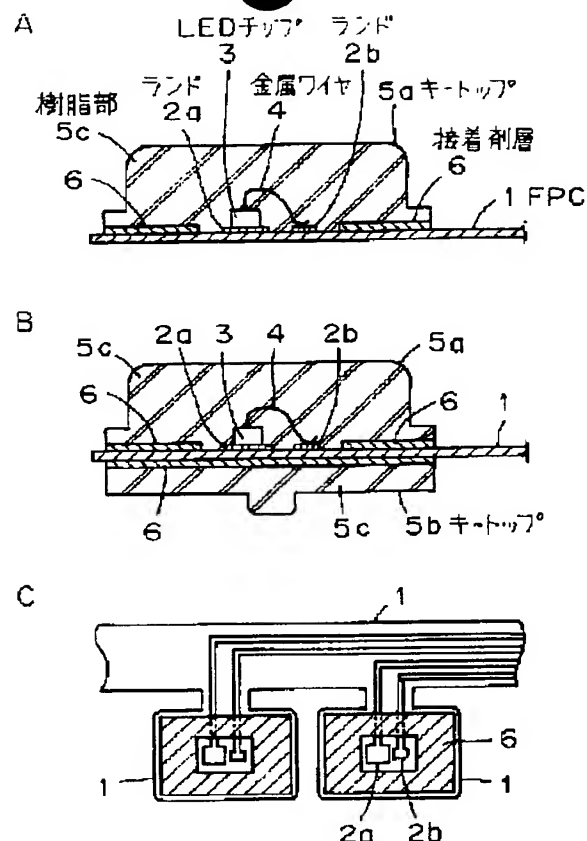
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TITLE : ILLUMINATION-TYPE KEYTOP



ABSTRACT : PURPOSE: To improve the manufacture yield by lessening the strain after forming and making a printing ink be taken well to a substrate.

CONSTITUTION: After a LED chip 3 is mounted on a FPC 1, a thermosetting adhesive layer 6 is formed on either only the front side or both the front and back sides of the FPC 1. A resin part 5c is formed on either the front side of both the front and the back sides by injection molding. As another method, without forming the adhesive layer 6, molding resin flow holes are formed in the FPC 1 and then resin injection molding is carried out while sandwiching the front and back sides of the FPC 1 with the resin. In any case, ABS resin or phenolic resin to which a printing ink can be taken well and which has no adhesive property, excellent formability, and is hardly strained after molding may be used.

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